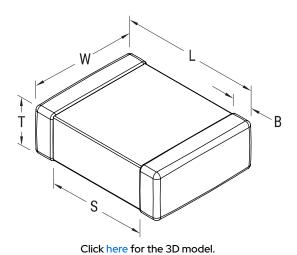


C0603C271K2TACTU

Aliases (C0603C271K2TAC7867)

SMD Comm X8G HT150C, Ceramic, 270 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	3.7 mg	
Shelf Life	78 Weeks	
MSL	1	

270 pF

1 MHz 1.0Vrms

100 GOhms

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

	•	
W	0.8mm +/-0.15mm	
Т	0.8mm +/-0.07mm	
S	0.5mm MIN	
В	0.35mm +/-0.15mm	
Design of the Control of the Control		

W	0.8mm +/-0.15mm	Tolerance	10%
Т	0.8mm +/-0.07mm	Voltage DC	200 VDC
S	0.5mm MIN	Dielectric Withstanding Voltage	500 VDC
В	0.35mm +/-0.15mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Paper Tape	Reference to +25°C and 0 VDC Applied (TCC)	., ,
Packaging Quantity	4000	Dissipation Factor	0.1% 1 MHz 1.0Vrms
	Dissipation i actor	0.176 TIVII 12 1.0 VIIII3	
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours

Specifications

Measurement Condition

Insulation Resistance

Capacitance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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